

## ABSTRACT OF THE DISCLOSURE:

TITLE: SYSTEM FOR TESTING ONE OR MORE GROUPS OF  
IC-CHIPS WHILE CONCURRENTLY LOADING/UNLOADING  
ANOTHER GROUP

An electromechanical system for testing IC-chips includes a total of N chip holding subassemblies, where N is an integer greater than one and where each chip holding subassembly has sockets for holding a group 5 of IC-modules that include the IC-chips; a moving mechanism for automatically moving the i-th chip holding subassembly from a load position in the system to a test position in the system, and visa-versa, where i ranges from 1 to N and changes with time in a sequence; and a 10 temperature control mechanism which contacts the IC-modules at the test position. Between the moving of the i-th chip holding subassembly and the next chip holding subassembly in the sequence, the IC-chips are burn-in tested on all N of the chip holding 15 subassemblies. Also, while the i-th chip holding subassembly is being moved, burn-in testing of IC-chips on the remaining N-1 chip holding subassemblies continues.